



EECS 3201: Digital Logic Design Lecture 1

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Quick Notes

- Course Name: Digital Logic Design, EECS 3201 (Any pharmacy or Music students here?!)
 - Lecturer: Me!, iamer@cse.yorku.ca
 - Office Hours: W & F after class
 - TAs: Jingbo Zhao and Arhum Sultana
 - Course Material: Textbook + Slides + Any notes posted on the course website or discussed during lectures/labs
 - Textbook:
 - Digital Design, 5th Edition, M. Morris, Mano and Michael D. Ciletti
 - Other References:
 - Fundamentals of Digital Logic with Verilog Design, 3rd Edition, S. Brown and Z. Vranesic
 - Digital Arithmetic, Ercegovic and Lang
 - Digital Design, 4th Edition, John Wakerly
 - Advanced Digital Logic Design, Sunggu Lee
 - Other references (if any) will be stated in the last slide of the lectures
 - Development Environment: Altera Quartus II

Course Policies

- Attending Lectures: **IMPORTANT!**
- Take notes during the lectures. Do **not** expect that everything said during the lecture will be documented in the slides
- I expect that anything “said” during a lecture or a lab session will be known by all students. So, if you do not attend, then please “at least” ask!
- It is your responsibility to check the course website regularly for any announcements or material
- I am open for *reasonable* interrupts during lectures for related questions

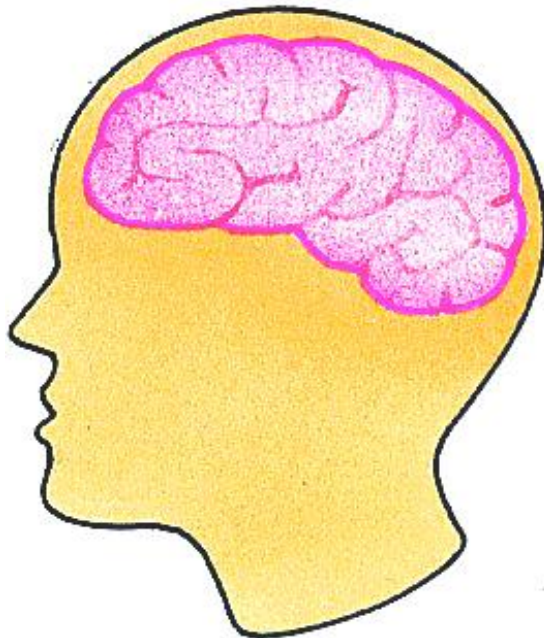
Course Assessment

- Assignments (10%)
 - Midterm (30%)
 - Labs/Project(s) (15%)
 - Final (45%)
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- Total (100%)

Course Objective

DVD, BD, MP3,
iPOD, PC, tablet,
camera, cell
phone, etc

Advanced
combinational and
sequential design,
FSM, ICs, Arith.
Circuits, Modern CAD
tools usage, HDL
(Verilog), FPGA, ... etc.



EECS 3201



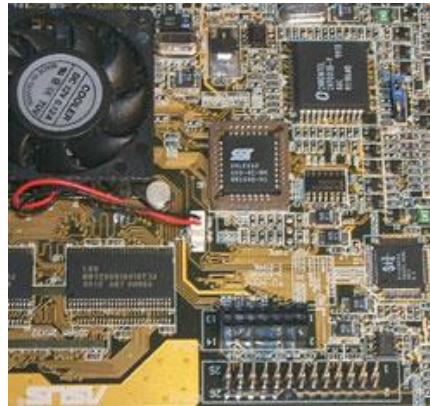
What student knows about the word “digital” before
EECS 3201

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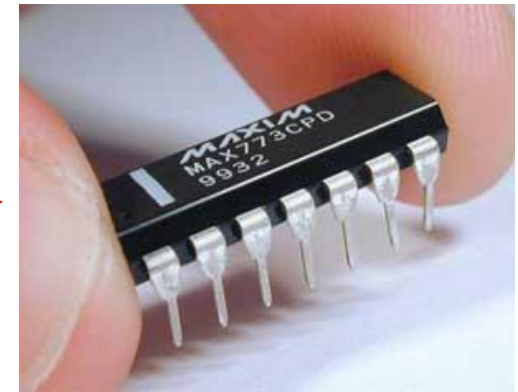
What's inside your computer?



Computer



PCB



IC

This course
introduces you to
the design process
of a typical IC

Integrated Circuits (ICs)

- Microelectronic *semiconductor* devices consisting of many interconnected transistors and other components
- Modern digital systems use ICs almost exclusively in their designs
- An IC is constructed ("fabricated") on a small rectangle (a "die") cut from a Silicon "wafer"
- Pure silicon is the basis for most integrated circuits. It provides the base, or *substrate* for the entire chip and is chemically doped to provide the N and P regions that make up the integrated circuit components
- ICs are small, reliable, cheap, and consume low power

→ *Quite a good deal!*

Where is an IC Fabricated?

- In a Fabrication Plant (Fab/Foundry)
- There are a few of them all-around the world
- Establishing a Fab costs billions of dollars

IC Market

IDMs

Fabless Companies

Merchant Foundries

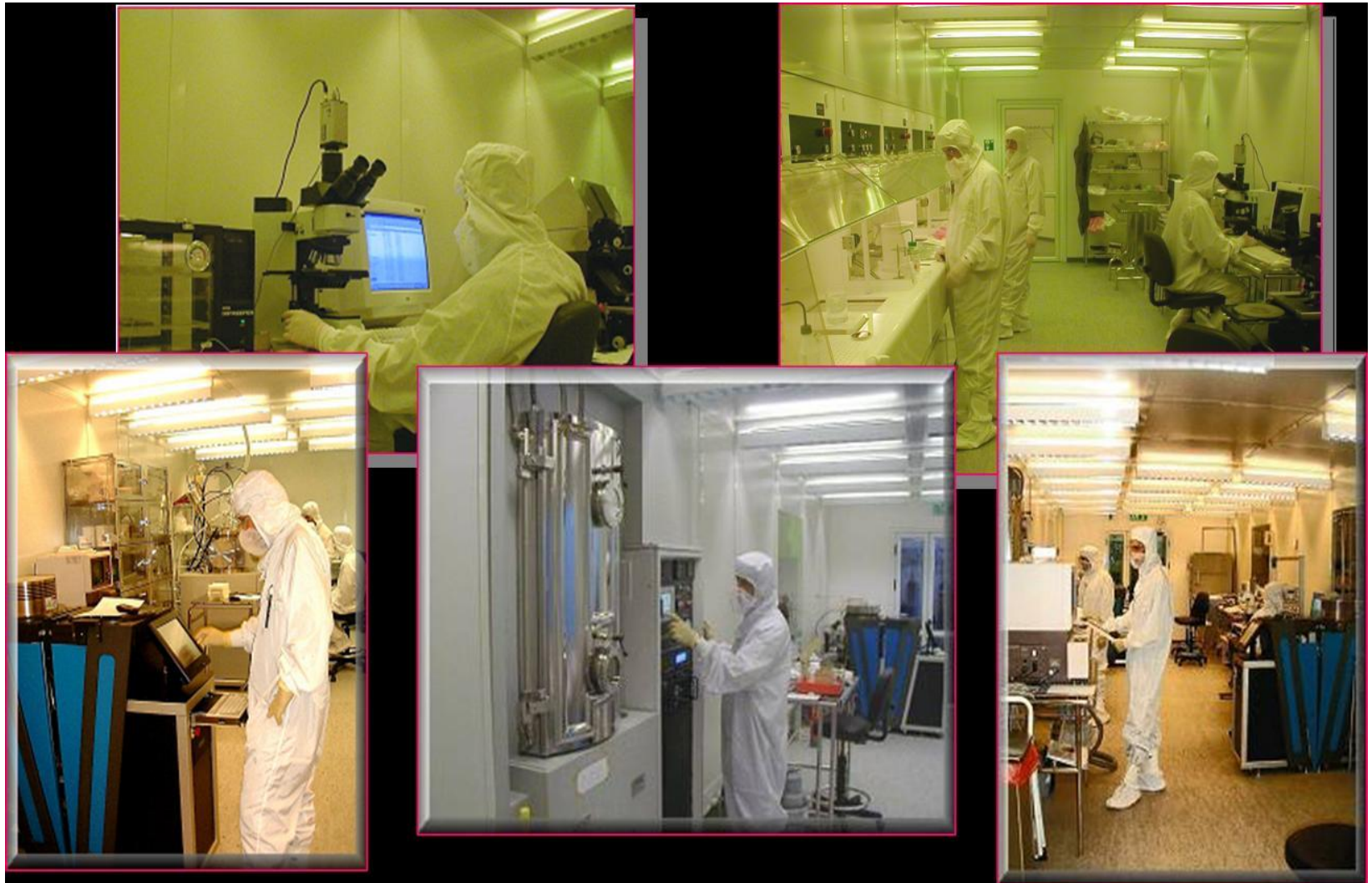
E.g. IBM, Intel,
Toshiba, TI, ...etc.

E.g. AMD, Qualcomm,
Broadcom, ... etc.

E.g. GF, TSMC, ... etc.

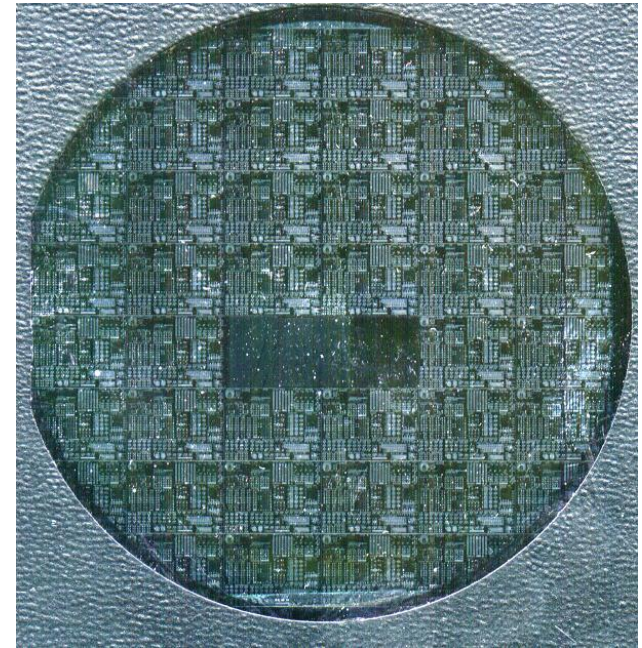
- This “Foundry Model” shows how business separates the design process from the manufacturing process

How does a Fab look like?



IC Manufacturing

- ICs are typically created on larger circular sheets of silicon called “wafers”
- A wafer is typically 100-300 mm in diameter, and about 4 mm thick
- A large silicon circuit is about 1 cm long
- In order to fabricate a number of chips, the wafer passes through thousands of steps including: thermal, chemical, cleaning, ... etc
- Each IC is tested before and after “packaging”



A Silicon wafer

Fabrication Yield

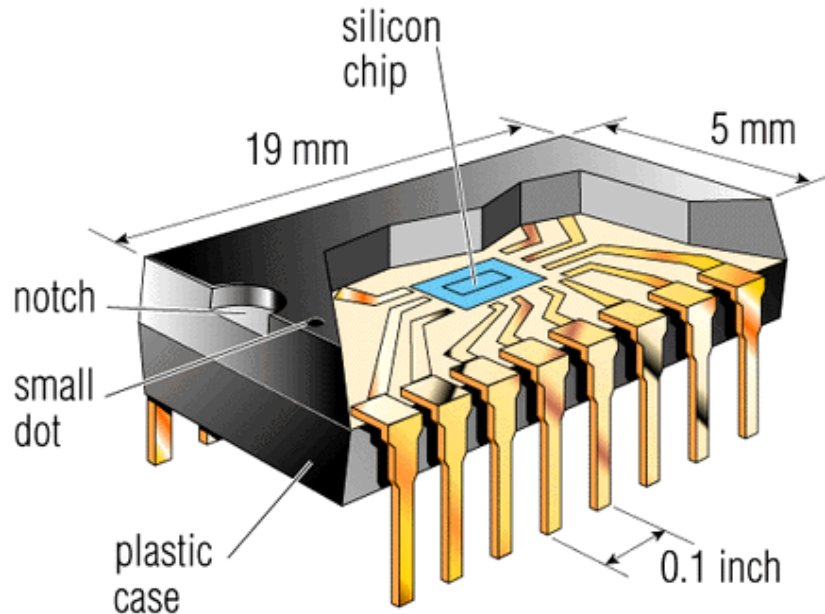
- Due to the complexity of the manufacturing process, not every site on a wafer turns out to be a functional circuit
- The *fabrication yield* is the percentage of good sites to the total set of sites

$$Y = \frac{N_G}{N_T} \times 100\% \quad , \text{ where } N_G \rightarrow \text{Number of Good (functional) sites}$$

$N_T \rightarrow \text{Total number of sites}$

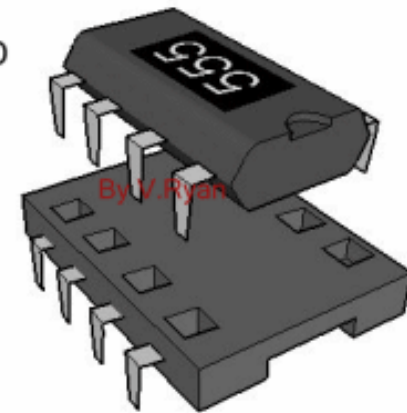
- A good chip design made by a good process will have more than 90% yield. A yield below 70% wastes too much material, losing money!

IC Package



INTEGRATED
CIRCUIT

CHIP
HOLDER



- The chip inside an IC is usually packaged inside a piece of black plastic with tiny pins protruding to allow connections to the circuit.
- It is often a good idea to solder a cheap chip holder to a PCB and then press the integrated circuit package into it

IC Classification

By type of signal



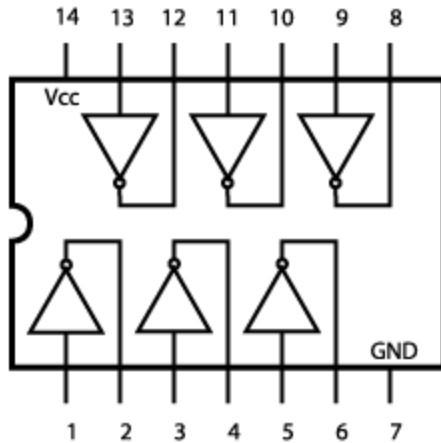
By complexity



By technology

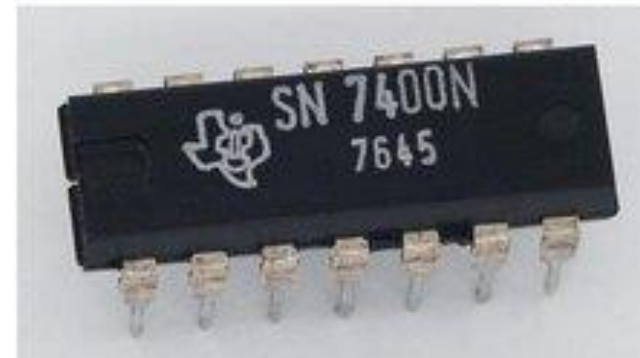
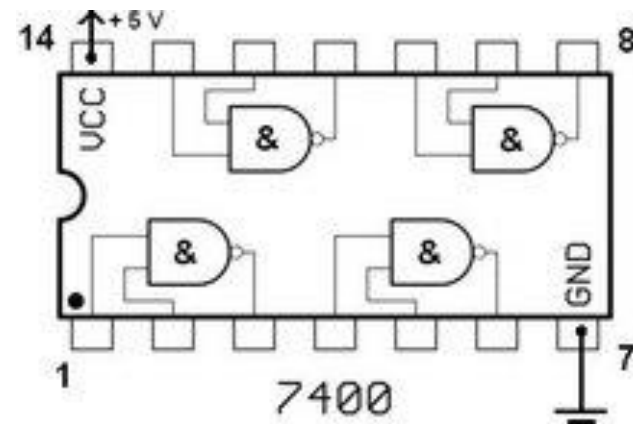


IC Examples



Input 1	1	14	VCC
Output 1	2	13	Input 6
Input 2	3	12	Output 6
Output 2	4	11	Input 5
Input 3	5	10	Output 5
Output 3	6	9	Input 4
Ground	7	8	Output 4

7404



7400

References

- “Digital Fundamentals (6th Edition)”, Thomas L. Floyd, Prentice Hall, 2002
- “Introduction to VLSI Circuits and Systems”, John P. Uyemura, Wiley, 2001
- <http://jjackson.eng.ua.edu/courses/ece380/lectures/>
- <http://www.cs.Berkeley.edu/~randy/Courses/CS150.F00/>
- <http://www.ece.msstate.edu/~reese/EE4743/>
- <http://www.wikipedia.com>